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SN74GTL16616 17-BIT LVTTL-TO-GTL/GTL+ UNIVERSAL BUS TRANSCEIVER WITH BUFFERED CLOCK OUTPUTS

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FEATURES

- Member of the Texas Instruments Widebus™
 Family
- UBT[™] Transceiver Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, Clocked, or Clock-Enabled Modes
- OEC[™] Circuitry Improves Signal Integrity and Reduces Electromagnetic Interference
- GTL Buffered CLKAB Signal (CLKOUT)
- Translates Between GTL/GTL+ Signal Levels and LVTTL Logic Levels
- Supports Mixed-Mode (3.3 V and 5 V) Signal Operation on A-Port and Control Inputs
- Equivalent to '16601 Function
- I_{off} Supports Partial-Power-Down Mode Operation
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors on A Port
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)

(TOP VIEW) 56 CEAB OEAB L LEAB 12 55 CLKAB 54 🛮 B1 A1 **∐**3 53 GND GND II4 52 B2 A2 [5 51 B3 A3 🛮 6 V_{CC} (3.3 V) **□**7 50 V_{CC} (5 V) A4 🛮 8 49 🛮 B4 A5 🛮 9 48 II B5 47 **∏** B6 A6 🏻 10 GND 11 46 GND A7 🛚 45 B7 12 44 🛮 B8 A8 🛮 13 A9 🛮 14 43 II B9 A10 🛮 15 42 B10 41 B11 A11 116 A12 117 40 B12 GND 1 18 39 **[]** GND A13 119 38 I B13 A14 1 20 37 B14 36 B15 A15 🛮 21 V_{CC} (3.3 V) 22 35 🛮 V_{REF} 34**∏** B16 A16 23 A17 🛮 24 33 **∏** B17 GND 125 32 GND CLKIN 26 31 CLKOUT OEBA 127 30 T CLKBA 29 CEBA LEBA 28

DGG OR DL PACKAGE

DESCRIPTION/ORDERING INFORMATION

The SN74GTL16616 is a 17-bit UBT™ transceiver that provides LVTTL-to-GTL/GTL+ and GTL/GTL+-to-LVTTL signal-level translation. Combined D-type flip-flops and D-type latches allow for transparent, latched, clocked, and clocked-enabled modes of data transfer identical to the '16601 function. Additionally, this device provides for a copy of CLKAB at GTL/GTL+ signal levels (CLKOUT) and conversion of a GTL/GTL+ clock to LVTTL logic levels (CLKIN). This device provides an interface between cards operating at LVTTL logic levels and a backplane operating at GTL/GTL+ signal levels. Higher-speed operation is a direct result of the reduced output swing (<1 V), reduced input threshold levels, and OEC™ circuitry.

ORDERING INFORMATION

T _A	Tube		ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	SSOP – DL	Tube	SN74GTL16616DL	GTL16616		
-40°C to 85°C	330P - DL	Tape and reel	SN74GTL16616DLR	GTL16616		
	TSSOP - DGG	Tape and reel	SN74GTL16616DGGR	GTL16616		

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The user has the flexibility of using this device at either GTL ($V_{TT}=1.2~V$ and $V_{REF}=0.8~V$) or the preferred higher noise margin GTL+ ($V_{TT}=1.5~V$ and $V_{REF}=1~V$) signal levels. GTL+ is the Texas Instruments derivative of the Gunning Transceiver Logic (GTL) JEDEC standard JESD 8-3. The B port normally operates at GTL or GTL+ signal levels, while the A-port and control inputs are compatible with LVTTL logic levels and are 5-V tolerant. V_{REF} is the reference input voltage for the B port. V_{CC} (5 V) supplies the internal and GTL circuitry, while V_{CC} (3.3 V) supplies the LVTTL output buffers.

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable (CEAB and CEBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CEAB is low and CLKAB is held at a high or low logic level. If LEAB is low, the A-bus data is stored in the latch/flip-flop on the low-to-high transition of CLKAB if CEAB also is low. When OEAB is low, the outputs are active. When OEAB is high, the outputs are in the high-impedance state. Data flow for B to A is similar to that of A to B, but uses OEBA, LEBA, CLKBA, and CEBA.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

Active bus-hold circuitry holds unused or undriven LVTTL inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE⁽¹⁾

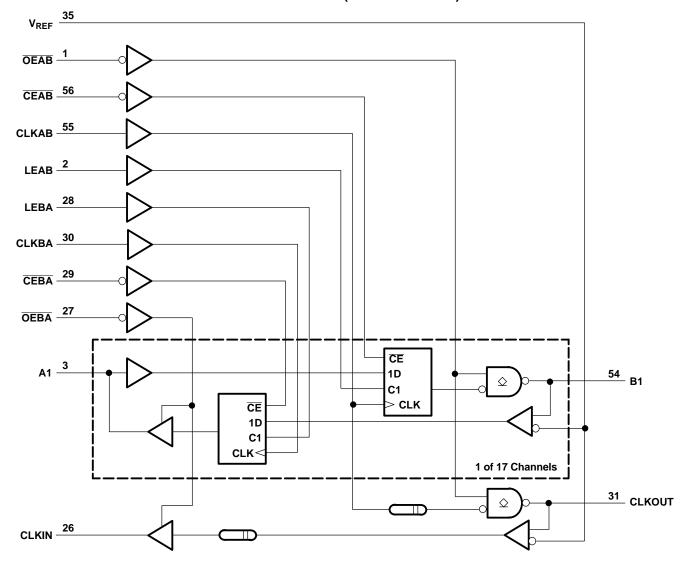
		INPUTS			OUTPUT	MODE
CEAB	OEAB	LEAB	CLKAB	Α	В	MODE
Х	Н	Х	Х	Х	Z	Isolation
L	L	L	Н	Χ	B ₀ ⁽²⁾	Latabad atarage of A data
L	L	L	L	X	B ₀ ⁽³⁾	Latched storage of A data
Х	L	Н	Х	L	L	Transparent
X	L	Н	Χ	Н	Н	Transparent
L	L	L	1	L	L	Clasked starons of A data
L	L	L	\uparrow	Н	Н	Clocked storage of A data
Н	L	L	Х	Х	B ₀ ⁽³⁾	Clock inhibit

- (1) A-to-B data flow is shown. B-to-A data flow is similar, but uses OEBA, LEBA, CLKBA, and CEBA. The condition when OEAB and OEBA are both low at the same time is not recommended.
- (2) Output level before the indicated steady-state input conditions were established, provided that CLKAB was high before LEAB went low
- (3) Output level before the indicated steady-state input conditions were established



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LOGIC DIAGRAM (POSITIVE LOGIC)



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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V	Cumply voltage range	3.3 V	-0.5	4.6	V	
V _{CC}	Supply voltage range	5 V	-0.5	7	V	
V	lanut valtaga ranga (2)	A-port and control inputs	-0.5	7	V	
VI	Input voltage range (2)	B port and V _{REF}	-0.5 4.6		V	
V	Valters range applied to any output in the high or never off state (2)	A port	-0.5	7	V	
Vo	Voltage range applied to any output in the high or power-off state (2)	B port	-0.5	4.6		
	Current into any output in the law state	A port		128	mA	
I _O	Current into any output in the low state	B port		80		
lo	Current into any A-port output in the high state ⁽³⁾			64	mA	
	Continuous current through each V _{CC} or GND			±100	mA	
I _{IK}	Input clamp current	V _I < 0		-50	mA	
I _{OK}	Output clamp current	V _O < 0		-50	mA	
0	Declare the world improduces (4)	DGG package		64	0C AA/	
θ_{JA}	Package thermal impedance (4)	DL package		56	°C/W	
T _{stg}	Storage temperature range		-65	150	°C	

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions (1)(2)(3)(4)

			MIN	NOM	MAX	UNIT	
	Complement	3.3 V	3.15	3.3	3.45	V	
V _{CC}	Supply voltage	5 V	4.75	5	5.25	V	
.,	Tamain ation walters	GTL		1.2	1.26	V	
V _{TT}	Termination voltage	GTL+	1.35	1.5	1.65	V	
.,	Defenses wellens	GTL	0.74	0.8	0.87		
V_{REF}	Reference voltage	GTL+	0.87	1	1.1	V	
.,	lanut valta aa	B port			V _{TT}	V	
VI	Input voltage	Except B port			5.5	V	
.,	Llieb lovel input voltage	B port V _{REF}				V	
V _{IH}	High-level input voltage	Except B port	2			V	
.,	Laur laurel innut voltage	B port			V _{REF} – 50 mV	V	
V_{IL}	Low-level input voltage	Except B port			8.0	V	
I _{IK}	Input clamp current				-18	mA	
I _{OH}	High-level output current	A port			-32	mA	
	Low level cutout current	A port			64	A	
I _{OL}	Low-level output current	B port			40	mA	
T _A	Operating free-air temperature	-40		85	°C		

⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

This current flows only when the output is in the high state and $V_O > V_{CC}$.

The package thermal impedance is calculated in accordance with JESD 51-7.

Normal connection sequence is GND first, V_{CC} = 5 V second, and V_{CC} = 3.3 V, I/O, control inputs, V_{TT} and V_{REF} (any order) last. V_{TT} and R_{TT} can be adjusted to accommodate backplane impedances if the dc recommended I_{OL} ratings are not exceeded.

 V_{REF} can be adjusted to optimize noise margins, but normally is two-thirds V_{TT} .



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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

P/			MAX	UNIT					
V _{IK}		V_{CC} (3.3 V) = 3.15 V,	V_{CC} (5 V) = 4.75 V,	I _I = -18 mA			-1.2	V	
. ,		V_{CC} (3.3 V) = 3.15 V to V_{CC} (5 V) = 4.75 V to 5		I _{OH} = -100 μA	V _{CC} - 0.2			.,	
V_{OH}	A port	V _{CC} (3.3 V) = 3.15 V,	\/ (5\/\ - 4.75\/	$I_{OH} = -8 \text{ mA}$	2.4			V	
		$v_{CC}(3.3 \text{ V}) = 3.13 \text{ V},$	V _{CC} (5 V) = 4.75 V	$I_{OH} = -32 \text{ mA}$	2				
				I_{OL} = 100 μ A			0.2		
	A port	V _{CC} (3.3 V) = 3.15 V,	V (5 \/\ - 4.75 \/	I _{OL} = 16 mA			0.4		
V_{OL}	A port	$v_{CC}(3.3 \text{ V}) = 3.13 \text{ V},$	$V_{CC}(5 V) = 4.75 V$	I_{OL} = 32 mA			0.5	V	
				$I_{OL} = 64 \text{ mA}$			0.55		
	B port	V_{CC} (3.3 V) = 3.15 V,	V_{CC} (5 V) = 4.75 V,	$I_{OL} = 40 \text{ mA}$			0.4		
	Control inputs	$V_{CC} = 0 \text{ or } 3.45 \text{ V},$				10			
				V _I = 5.5 V			20		
	A port	V_{CC} (3.3 V) = 3.45 V,	V_{CC} (5 V) = 5.25 V	$V_{I} = V_{CC} (3.3 \text{ V})$			1	^	
I _I				V _I = 0			-30	μА	
	Donat	V (0.0.V) 0.45.V	\\ (5\\\) 5.05\\	$V_{I} = V_{CC} (3.3 \text{ V})$			5		
	B port	V_{CC} (3.3 V) = 3.45 V,	$V_{CC} (5 V) = 5.25 V$	V _I = 0			-5		
l _{off}	T.	$V_{CC} = 0$,	V_{1} or $V_{0} = 0$ to 4.5 V				100	μΑ	
				V _I = 0.8 V	75				
I _{I(hold)}	A port	V_{CC} (3.3 V) = 3.15 V,	V_{CC} (5 V) = 4.75 V	V _I = 2 V	-75			μΑ	
, ,				$V_I = 0$ to $V_{CC} (3.3 \text{ V})^{(2)}$			±500		
	A port	V_{CC} (3.3 V) = 3.45 V,	V_{CC} (5 V) = 5.25 V,	V _O = 3 V			1	^	
I _{OZH}	B port	V_{CC} (3.3 V) = 3.45 V,	V_{CC} (5 V) = 5.25 V,	V _O = 1.2 V			10	μΑ	
	A port	V_{CC} (3.3 V) = 3.45 V,	V_{CC} (5 V) = 5.25 V,	V _O = 0.5 V			-1		
l _{OZL}	B port	V_{CC} (3.3 V) = 3.45 V,	V_{CC} (5 V) = 5.25 V,	V _O = 0.4 V			-10	μΑ	
		V_{CC} (3.3 V) = 3.45 V,		Outputs high			1		
I _{CC} (3.3 V)	A or B port	V_{CC} (5.3 V) = 5.25 V, I_{O} =	= 0,	Outputs low			5	mA	
(3.3 V)		$V_I = V_{CC} (3.3 \text{ V}) \text{ or GNI}$)	Outputs disabled			1		
		V_{CC} (3.3 V) = 3.45 V,		Outputs high			120		
I _{CC} (5 V)	A or B port	V_{CC} (5 V) = 5.25 V, I_{O} =		Outputs low			120	mA	
(3 V)		$V_I = V_{CC}$ (3.3 V) or GNE)	Outputs disabled					
V_{CC} (3.3 V) = 3.45 V, V_{CC} (5 V) = 5.25 V, A-port or control inputs at V_{CC} (3.3 V) or GND, One input at 2.7 V		e input at 2.7 V			1	mA			
Ci	Control inputs	V _I = 3.15 V or 0				3.5		pF	
<u></u>	A port	V _O = 3.15 V or 0				12		~ ٦	
C_{io}	B port	Per IEEE Std 1194.1			5	pF			

All typical values are at V_{CC} (3.3 V) = 3.3 V, V_{CC} (5 V) = 5 V, T_A = 25°C. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to (2) another.

This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.



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Timing Requirements

over recommended ranges of supply voltage and operating free-air temperature, $V_{TT}=1.2~V$ and $V_{REF}=0.8~V$ for GTL (unless otherwise noted) (see Figure 1)

			MIN	MAX	UNIT
f _{clock}	Clock frequency			95	MHz
	Pulse duration	LEAB or LEBA high	3.3		20
t _w	Fuise duration	CLKAB or CLKBA high or low	5.5		ns
		A before CLKAB↑	1.3		
		B before CLKBA↑	2.5		
	Catura time	A before LEAB↓	0		20
t _{su}	Setup time	B before LEBA↓	1.1		ns
		CEAB before CLKAB↑	2.2		
		CEBA before CLKBA↑	2.7		
		A after CLKAB↑	1.6		
		B after CLKBA↑	0.4		
	الماط فنجم	A after LEAB↓	4		
t _h	Hold time	B after LEBA↓	3.5		ns
		CEAB after CLKAB↑	1.1		
		CEBA after CLKBA↑	0.9		



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Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature, V_{TT} = 1.2 V and V_{REF} = 0.8 V for GTL (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP ⁽¹⁾	MAX	UNIT	
f _{max}			95			MHz	
t _{PLH}	A	В	1.7	3	4.4	ns	
t _{PHL}	A	В	1.4	2.8	4.5	115	
t _{PLH}	LEAB	В	2.3	3.8	5.4	ns	
t _{PHL}	LEAD	Б	2.2	3.7	5.3	115	
t _{PLH}	CLKAB	В	2.4	4	5.7	no	
t _{PHL}	CLNAD	Б	2.1	3.7	5.4	ns	
t _{PLH}	CLKAB	CLKOUT	4.7	6.1	8.1	no	
t _{PHL}	CLNAD	CLKOUT	5.7	7.9	11.3	ns	
t _{PHL}	OEAB	B or CLKOUT	2.1	3.6	5.1	ns	
t _{PLH}	OEAB	B OI CLROOT	2.1	3.8	5.6	115	
t _r	Transition time, B o		1.2		ns		
t _f	Transition time, B o	utputs (1 V to 0.5 V)		0.7		ns	
t _{PLH}	В	A	1.7	4	6.7	ns	
t _{PHL}	ь	A	1.4	2.9	4.7		
t _{PLH}	LEBA	A	2.4	3.8	5.8	ns	
t _{PHL}	LEBA	A	2	3	4.6	115	
t _{PLH}	CLKBA	A	2.6	4	6	ns	
t _{PHL}	CLNDA	^	2.2	3.4	4.9	115	
t _{PLH}	CLKOUT	CLKIN	7.4	10	14.4	nc	
t _{PHL}	CLROUT	CLNIN	6.1	8.1	11.7	ns	
t _{en}	ОЕВА	A or CLKIN	2.8	5.3	7.8	ns	
t _{dis}	UEDA	A UI CLNIN	2.7	4.3	6.4		

⁽¹⁾ All typical values are at V_{CC} (3.3 V) = 3.3 V, V_{CC} (5 V) = 5 V, T_A = 25°C.



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Timing Requirements

over recommended ranges of supply voltage and operating free-air temperature, V_{TT} = 1.5 V and V_{REF} = 1 V for GTL+ (unless otherwise noted) (see Figure 1)

			MIN	MAX	UNIT
f _{clock}	Clock frequency			95	MHz
+	Pulse duration	LEAB or LEBA high	3.3		20
t _w	ruise duration	CLKAB or CLKBA high or low	5.5		ns
		A before CLKAB↑	1.3		
		B before CLKBA↑	2.3		
	s _{su} Setup time	A before LEAB↓	0		
t _{su} Set	Setup time	B before LEBA↓	1.3		ns
		CEAB before CLKAB↑	2.2		
		CEBA before CLKBA↑	2.7		
		A after CLKAB↑	1.6		
		B after CLKBA↑	0.6		
	Hald time	A after LEAB↓	4		
t _h	Hold time	B after LEBA↓	3.5		ns
		CEAB after CLKAB↑	1.1		
		CEBA after CLKBA↑	0.9		



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Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature, V_{TT} = 1.5 V and V_{REF} = 1 V for GTL+ (see Figure 1)

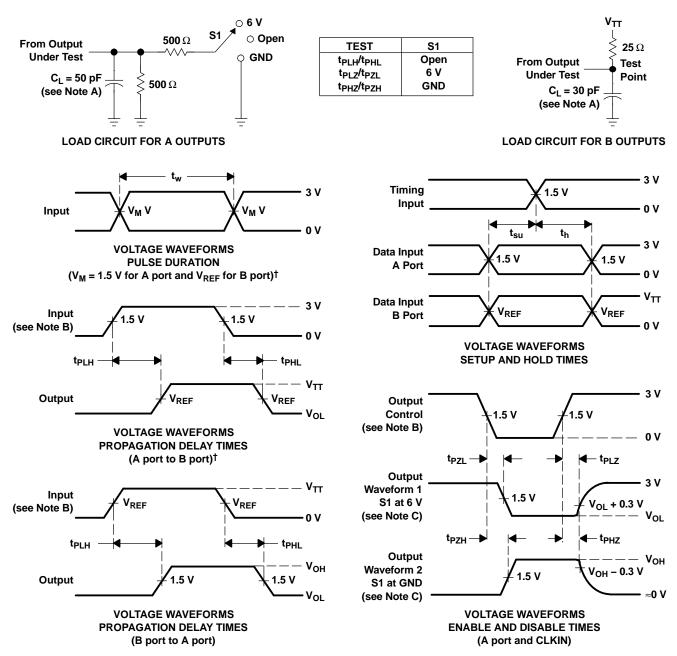
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP ⁽¹⁾	MAX	UNIT
f _{max}			95			MHz
t _{PLH}	А	В	1.7	3	4.4	ns
t _{PHL}	A	В	1.4	2.9	4.6	113
t _{PLH}	LEAB	В	2.3	3.8	5.4	ns
t _{PHL}	LEAD	Б	2.2	3.7	5.4	115
t _{PLH}	CLKAB	В	2.4	4	5.7	20
t _{PHL}	CLRAB	Б	2.1	3.8	5.5	ns
t _{PLH}	CLKAB	CLKOUT	4.7	6.1	8.1	20
t _{PHL}	CLRAB	CLROOT	5.7	8	11.4	ns
t _{PLH}	<u>OEAB</u>	B or CLKOUT	2.1	3.6	5.1	ns
t _{PHL}	OEAB	B of CLKOUT	2.1	3.8	5.7	
t _r	Transition time, B o		1.4		ns	
t _f	Transition time, B o	utputs (1 V to 0.5 V)		1		ns
t _{PLH}	В	А	1.6	3.9	6.6	ns
t _{PHL}	Ь	A	1.3	2.8	4.5	
t _{PLH}	LEBA	A	2.4	3.8	5.8	20
t _{PHL}	LEBA	^	2	3	4.6	ns
t _{PLH}	CLKBA	A	2.6	4	6	ns
t _{PHL}	CLNBA	^	2.2	3.4	4.9	115
t _{PLH}	CLKOUT	CLKIN	7.3	9.9	14.3	20
t _{PHL}	CLROUT	CLKIN	6	8	11.5	ns
t _{en}	ŌĒBĀ	A or CLKIN	2.8	5.3	7.8	20
t _{dis}	UEDA	A OI CLNIN	2.7	4.3	6.4	ns

⁽¹⁾ All typical values are at V_{CC} (3.3 V) = 3.3 V, V_{CC} (5 V) = 5 V, T_A = 25°C.

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PARAMETER MEASUREMENT INFORMATION V_{TT} = 1.2 V, V_{REF} = 0.8 V FOR GTL AND V_{TT} = 1.5 V, V_{REF} = 1 V FOR GTL+



[†] All control inputs are TTL levels.

NOTES: A. C₁ includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN74GTL16616DLR	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	GTL16616
SN74GTL16616DLR.B	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	GTL16616

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

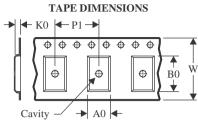
⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

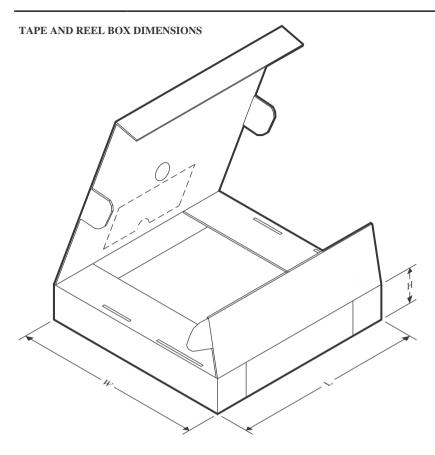


*All dimensions are nominal

	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
j	SN74GTL16616DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	SN74GTL16616DLR	SSOP	DL	56	1000	356.0	356.0	53.0

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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